



ENVIRONMENTAL AND PACKAGE TESTING DATA FOR SOT-23					
STRESS	SAMPLE SIZE	DEVICE HR./CYC	CONDITION	TOTAL FAILS	FAIL PERCENTAGE
BOND INT	320	160 000	200 °C + N2	0	0.00
HAST	1680	168 000	130 °C, 85 % RH	0	0.00
Pressure Pot	3600	345 600	121°, 15 PSIG	0	0.00
Solder DUNK	670	2010	260 °C, 10 s	0	0.00
Solderability	725	2140	883 M2003	0	0.00
Temp. Cycle	5700	2 675 000	- 65 °C to 150 °C	0	0.00